

CALL FOR PAPERS

The Leading International Components, Packaging, and Manufacturing Technology Symposium



12th IEEE CPMT Symposium Japan

The abstract submission deadline has been extended to June 12, 2023.

November 15 – 17, 2023,

Venue: Ritsumeikan University Suzaku Campus, Kyoto, JAPAN (On-site only)

<https://www.ieee-csj.org/>

“Advanced Packaging for Chiplet Era”

“IEEE CPMT Symposium Japan (ICSJ)” is one of the most widely recognized international conferences sponsored by the **IEEE Electronics Packaging Society (EPS)** and has been held annually in Kyoto in November. This conference was inaugurated in 1992 as “The VLSI Packaging Workshop in Japan (VPWJ)” to provide a platform for you to communicate and interact with global leaders in packaging technology. Later in 2010, this conference was renamed to “ICSJ” and ICSJ2023 is the 12th ICSJ meeting, or 21th conference since establishing VPWJ. The past two years of ICSJ events were a hybrid meeting with virtual and on-site event, but this year, ICSJ2023 will be only on-site meetings since the pandemic settles down and our daily things get to the normal.

Advanced Packaging for Chiplet Era: Chiplet architecture, moving from monolithic to multi-tile devices, is becoming a key technology to expand computing resources with integrated functional units on a same package. Chiplet is not only driving the packaging technology including 2.xD/3D integration and high density substrate technology with process and material, but also revolutionizing applications requiring highly advanced computing such as 5G, AI, automotive, edge computing and mobile components. The symposium tries to forecast where the packaging technology is heading. In 2023, our focus is on key electronics packaging technologies pulling by Chiplet architecture on the following main topics: **Photonics, Advanced Packaging, Process & Material, Power & Automotive Electronics, Bioelectronics & Healthcare**, and **Signal/Power Integrity**. Additional topics of primary interest to the participants are listed below.

Other topics include (but not limited to):

- + Fine Pitch Assembly & Hybrid bonding
- + Packaging for Neuromorphic or Quantum computing
- + Laminated Materials & Processing
- + Co-packaged Optics & Materials for optical packaging
- + Packaging for High-Speed Electrical Interconnect
- + Chiplet Design, Signal Integrity & Power Integrity
- + RF Components & Modules
- + Additive Manufacturing & 3D Printed Electronics
- + Resilient Packaging for Autonomous System
- + Low Power, Low Temperature & Ultra Low Noise System Packaging



This conference is a perfect opportunity for you to communicate, interact, exchange technical ideas, and discuss your latest novel research findings in packaging technologies with experts from industry and academia. In addition to the regular sessions, there is an “Early Career Researchers’ (ECR)” session for young researchers with less than 2-year experience in their professions and all students including Ph.D. to hold fruitful communications with the experts. The ECR sessions will be held as a poster session. Authors are invited to submit an abstract through our website <https://www.ieee-csj.org/>. **The abstract deadline has been extended from May 29, 2023 to June 12, 2023.** Notification of acceptance will be sent by July 14, 2023, and the authors are requested to submit a 4-page manuscript by September 11, 2023 for the Technical Digest which will be available via **IEEE Xplore Digital Library**, whereas the authors for the ECR session are required to submit a 2-page manuscript.

Plenary, Special Session Speakers:

As of May 2023, the confirmed speakers are listed below:

Plenary Speakers:

Seungwook Yoon (Samsung Electronics)

Special Session Speakers:

Rer. Nat. Harald Kuhn (Fraunhofer ENAS)
Sam Karikalan (Broadcom Inc.)

Invited Speakers:

Gari Arutinov (Holst Centre)
Mami N. Fujii (Kindai University)

The above list of speakers will be updated and announced on the ICSJ official website.

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Financial Sponsor:

IEEE Electronics Packaging Society (EPS)

Cooperation:

IEEE EPS Japan Chapter Section

On-site Conference Venue:

Ritsumeikan University Suzaku Campus
Nishinokyosuzakucho 1, Nakagyoku, Kyoto, 604-8520

